PRODUCT ADVANTAGE

Low & High Temperature Curing Options
Conductive & Insulating Materials
High Thermal & Electrical Conductivity
Low Temperature Cure for High Temperature Applications
High Reliability
No Delamination

OUR THREE PILLARS

1. EXCEEDING PERFORMANCE SPECIFICATIONS
2. MAXIMIZING PRODUCTIVITY
3. LOWERING PROCESS COST

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YPB-006 (Version 5/2017)
YINCAE® Die Attach Adhesives

YINCAE® TM solderable conductive adhesive products are rapid cure, self-filling, self-leveling, and self-soldering. They can be used as die attach adhesives for various devices, including LED, CSP, QFP..., to replace conductive adhesives (Ag) or solder materials.

Benefits:
- High thermal conductivity
- No outgassing, die shifting, or die skewing

Featured Products:
- **TM 158**: diamond filled, high thermal conductivity (60 W/mK), and can withstand very high temperature (400°C) applications
- **TM 230**: ultra-quick, 60 seconds, cure and high thermal conductivity (58 W/mK)

<table>
<thead>
<tr>
<th>Product</th>
<th>Product Application</th>
<th>Curing Temp. (°C)</th>
</tr>
</thead>
<tbody>
<tr>
<td>DA 90</td>
<td>Silver filled, conductive adhesive</td>
<td>80 – 110</td>
</tr>
<tr>
<td>DA 90B</td>
<td>Silver filled, conductive adhesive</td>
<td>80 – 110</td>
</tr>
<tr>
<td>DA 90LV</td>
<td>Insulating adhesive for LED chip bonding</td>
<td>80 – 110</td>
</tr>
<tr>
<td>DA 90UV</td>
<td>Insulating adhesive for optoelectronic devices</td>
<td>80 – 110</td>
</tr>
<tr>
<td>DA 150</td>
<td>Silver filled, conductive adhesive</td>
<td>150</td>
</tr>
<tr>
<td>DA 150E</td>
<td>Insulating adhesive for LED chip bonding</td>
<td>150</td>
</tr>
<tr>
<td>DA 150S</td>
<td>Silica filled, insulating adhesive</td>
<td>150</td>
</tr>
<tr>
<td>DA 150U</td>
<td>Insulating adhesive for GaN bonding</td>
<td>150</td>
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<tr>
<td>TM 150</td>
<td>Silver filled, solderable conductive adhesive</td>
<td>180</td>
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<tr>
<td>TM 150E</td>
<td>Silver filled, solderable conductive adhesive</td>
<td>190</td>
</tr>
<tr>
<td>TM 230</td>
<td>Silver filled, solderable conductive adhesive</td>
<td>230</td>
</tr>
</tbody>
</table>

YINCAE® TM series products show the lowest change in temperature suggesting they have the highest thermal conductivity.

Contact YINCAE at info@yincae.com for detailed specifications & customization for your specific product requirements.